HF-800MHz, 200W, 50V RF LDMOS FETs

Description

The MU1020V is a 200-watt, highly rugged, unmatched LDMOS FET, designed for wide-band commercial and industrial applications at frequencies HF to 800MHz.

•Typical Performance (On Innogration narrow band fixture with device soldered): CW , VDS=48V, VGS=3.3V, Idq=200mA

•		•			
Freq(MHz)	Pin(dBm)	Pout(dBm)	IDS(A)	Gain(dB)	EFF(%)
410	36.3	53.1	7.4	16.8	57.5%
420	36.1	53.3	7.6	17.2	58.6%
440	36	53.5	7.7	17.5	60.6%
460	36.2	53.5	7.8	17.3	59.8%
480	36.2	53.8	8.4	17.6	59.5%
500	36.5	53.9	8.9	17.4	57.5%
520	36.8	54	9.3	17.2	56.3%
540	35.8	53.9	9.1	18.1	56.2%
560	34.9	53.7	8.4	18.8	58.1%
580	35	53.5	7.9	18.5	59.0%
600	36	53	6.9	17	60.2%

MU1020V

Features

- · High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

Suitable Applications

- 2-30MHz (HF or Short wave communication)
- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 118 -140MHz (Avionics)

- 136-174MHz (Commercial ground communication)
- 160-230MHz (TV VHF III)
- 30-512MHz (Jammer, Ground/Air communication)
- 470-860MHz (TV UHF)
- 100kHz 1000MHz (ISM, instrumentation)

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	120	Vdc
GateSource Voltage	V_{GS}	-10 to +10	Vdc
Operating Voltage	V_{DD}	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	Τ _J	+225	°C

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Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Po IO	0.59	°C/W
T _C = 85°C, T _J =200°C, DC test	R⊕JC	0.58	-0/00

Table 3. ESD Protection Characteristics

Test Methodology	Class	
Human Body Model (per JESD22A114)	Class 2	

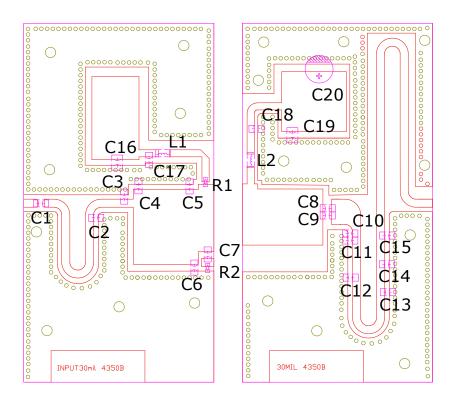
Table 4. Electrical Characteristics (TA = 25 ℃ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
DC Characteristics					
Drain-Source Voltage	V		122		V
V _{GS} =0, I _{DS} =1.0mA	$V_{(BR)DSS}$		122		'
Zero Gate Voltage Drain Leakage Current				1	^
$(V_{DS} = 50V, V_{GS} = 0 V)$	I _{DSS}			Į	μА
GateSource Leakage Current				4	
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$	I _{GSS}			1	μА
Gate Threshold Voltage	V (0)		2.73		V
$(V_{DS} = 50V, I_D = 600 \mu A)$	V _{GS} (th)		2.73		V
Gate Quiescent Voltage	V		3.3		V
(V_{DD} = 50 V, I_{D} = 200 mA, Measured in Functional Test)	$V_{GS(Q)}$		3.3		V
Common Source Input Capacitance	C _{ISS}		150		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$					
Common Source Output Capacitance	Coss		56		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$					
Common Source Feedback Capacitance	C _{RSS}		1.6		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$					

Functional Tests (In Demo Test Fixture, 50 ohm system) V_{DD} = 48 Vdc, I_{DQ} = 100mA, f = 600 MHz, CW Signal Measurements, Pin=36dBm

Power Gain@Pout	Gp		17	 dB
Output Power	Pout	30	200	W
Drain Efficiency@Pout	η _D		60	 %
Input Return Loss	IRL		-7	 dB

Reference Circuit of Test Fixture Assembly Diagram 410-600MHz Class AB (Layout file upon request,)



Test Circuit Component Designations and Values

Component	Description	Suggested Manufacturer	
C1	100pF	ATC600F	
C2,	15pF	ATC800B	
C3	6.8pF	ATC800B	
C4	20pF	ATC800B	
C5, C6, C10	24pF	ATC800B	
C8, C9, C17, C18	56pF	ATC600F	
C11	8.2pF	ATC800B	
C12	18pF	ATC800B	
C13, C14	4.7pF	ATC800B	
C15	3.3pF	ATC800B	
C7, C16, C19	10uF 100V	Ceramic multilayer capacitor	
C20	470uF,63V	Electrolytic Capacitor	
R1, R2	9.1 Ω , 1206	Chip Resistor	
L1, L2	10nH	DIY air core inductance	
PCB	PCB 0.762mm [0.030"] thick, εr=3.50, Rogers 4350B, 1 oz. copper		

Package Outline

Flanged ceramic package; 2 leads

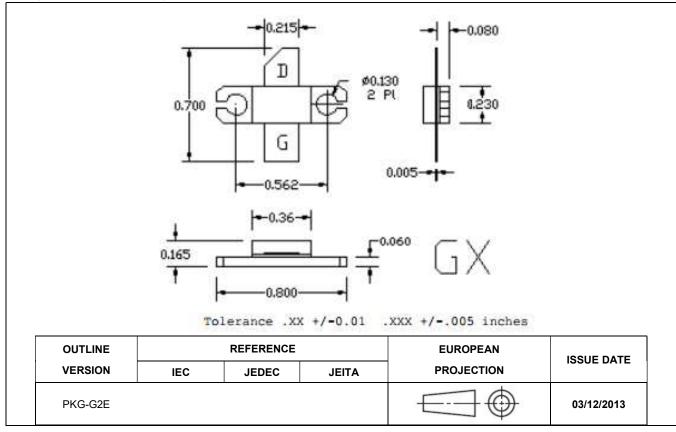


Figure 1. Package Outline PKG-G2E

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Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2021/6/11	V1.0	Preliminary Datasheet Creation

Application data based on TK-21-03

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